

Request for confidentiality: explanation

Date: 16/07/2024

Document: Internal Photos

Product: TMS AP-01

FCC ID: FI5TMSAP01

During the production process of the TMS AP-01, its circuit board and cell are placed in a mold and overmolded with a black thermoplastic polyamide (below a picture of the product before and after overmolding process and the mold).

After the material is cooled, during the last step of the production process, it's impossible to remove the thermoplastic without permanently damaging the product.

That why we request long term confidentiality for the internal photos of the TMS AP-01 product.



MICHELIN NORTH AMERICA (US) INC.

Jessica SHEARER

Sign:

Jassie Shearer